

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

## D24V0L1B2LPS-7B

Product specification

**Features**

- IEC61000-4-2 (ESD) ±8kV (Contact)
- ±15kV (Air)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lighting) 3A(8/20μs)
- 100 Watts Peak Pulse Power (tp=8/20μs)
- Working voltages : 24V
- Low clamping voltage
- Low leakage current

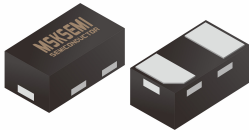
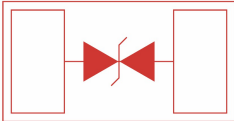

**Applications**

- Serial and Parallel Ports
- Notebooks, Desktops, Servers
- Projection TV
- Cellular handsets and accessories
- Portable instrumentation
- Peripherals

**Mechanical Characteristics**

- DFN1006 package
- Flammability Rating: UL 94V-0
- Packaging: Tape and Reel
- Reel size: 7 inch

**Reference News**

PACKAGE OUTLINE	Circuit Diagram	Marking
 DFN1006		

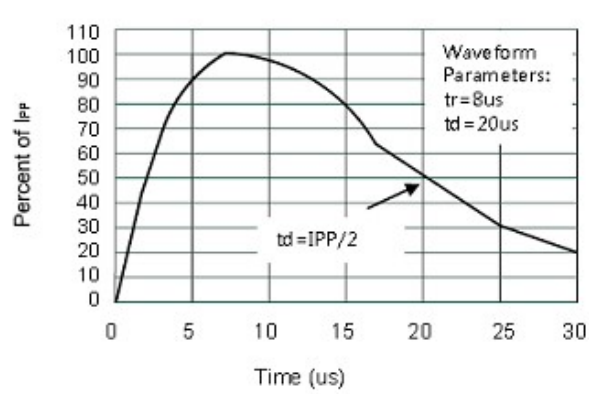
**ABSOLUTE MAXIMUM RATING**

Symbol	Parameter	Value	Units
$V_{ESD}$	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	$\pm 8$ $\pm 15$	kV
$P_{PP}$	Peak Pulse Power (8/20 $\mu$ s)	150	W
$T_{OPT}$	Operating Temperature	-55 ~ +125	°C
$T_{STG}$	Storage Temperature	-55 ~ +150	°C
$T_L$	Lead Soldering Temperature	260 (10 sec.)	°C

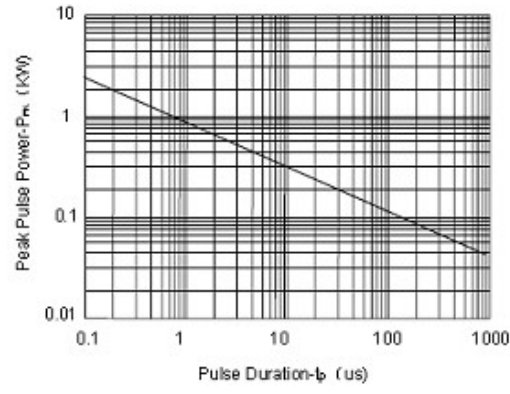
**ELECTRICAL CHARACTERISTICS (Tamb=25°C)**

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
$V_{RWM}$	Reverse Working Voltage				24	V
$V_{BR}$	Reverse Breakdown Voltage	$I_T = 1mA$	26		32	V
$I_R$	Reverse Leakage Current	$V_{RWM} = 24V$			1	$\mu A$
$V_{C1}$	Clamping Voltage 1	$I_{PP} = 1A, t_p = 8/20\mu s$			40	V
$V_{C2}$	Clamping Voltage 2	$I_{PP} = 3A, t_p = 8/20\mu s$			50	V
$C_J$	Junction Capacitance	$V_R = 0V, f = 1MHz$		8	15	pF

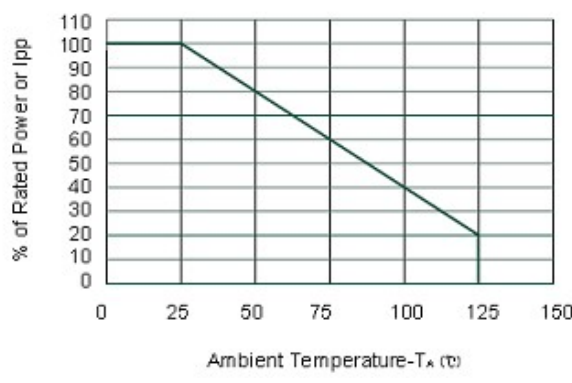
ELECTRICAL CHARACTERISTICS CURVE



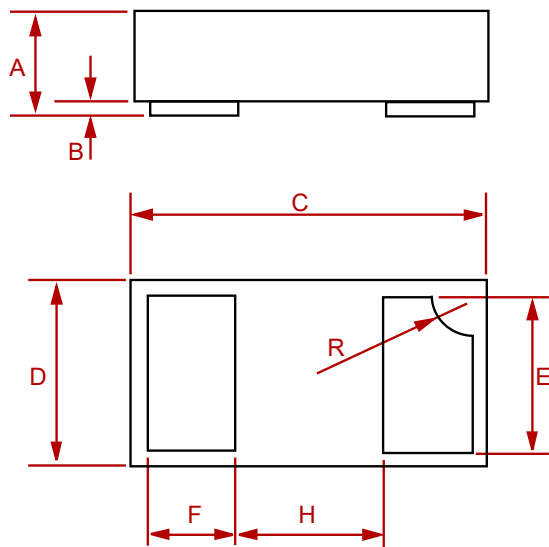
Pulse Waveform



Non-Repetitive Peak Pulse Power vs. Pulse Time

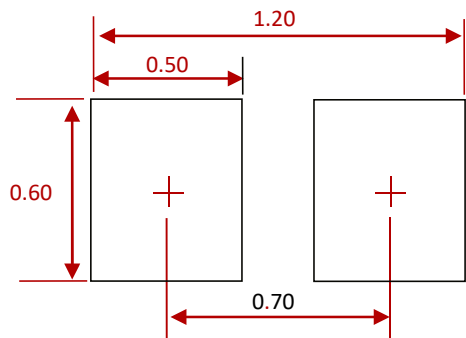


**PACKAGE MECHANICAL DATA**



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

**Suggested Pad Layout**



- NOTES:
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
  2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.  
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR  
COMPANY'S MANUFACTURING GUIDELINES ARE MET.

**REEL SPECIFICATION**

P/N	PKG	QTY
D24V0L1B2LPS-7B	DF1006	10000

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